LISTING OF THE CLAIMS

1. (Currently Amended) A fabrication method of a liquid crystal display panel, comprising:

forming a substrate including a plurality of thin film transistor array, the thin film transistor array having a thin film transistor at crossings of gate lines and data lines formed on a substrate, a gate pad part including a gate pad connected to the gate line and a data pad part including a data pad connected to the data line;

preparing a cutting-off plate having an opening region overlapped with the pad part of the substrate and a cutting-off region overlapped with a remainder part other than the pad part of the substrate;

arranging a the cutting-off plate on the substrate so that the opening region overlaps with the pad part and the cutting-off region overlaps with the remainder part a remainder region of the substrate other than the region of the pad part; and

exposing <u>all</u> of the gate pad <u>and the data pad protection electrode</u> of the pad part and the data pad protection electrode by a etching process using the cutting-off plate, wherein the eutting-off plate is capable of being etched along with the protective film in the etching process;

wherein the step of forming the thin film transistor array substrate comprises the steps of:

forming a gate pattern including a gate electrode of the thin film transistor, the gate line connected to the gate electrode and the gate pad connected to the gate line on the substrate by use of a first masking process;

forming a gate insulation film on the substrate where the gate pattern is formed;

forming a source electrode and a drain electrode of the thin film transistor, a data line connected to the source electrode, a data pad connected to the data line, a source/drain pattern including a storage electrode in a region overlapped with the gate line, a semiconductor pattern formed in the lower part according to the source/drain pattern on the gate insulation film by use of a second masking process;

forming a transparent electrode pattern including a pixel electrode and a data pad protection electrode by use of a third masking process, the pixel electrode is directly connected to the drain electrode and the storage electrode, and the data pad protection electrode is formed for covering the data pad; and

forming entirely a protection film on the substrate.

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- 2. (Original) The fabrication method of the liquid crystal display panel according to claim 1, wherein a step of assembling a thin film transistor array substrate and a color filter array substrate where the gate pad and the data pad protection electrode are exposed, is further comprised.
- 3. (Original) The fabrication method of the liquid crystal display panel according to claim 1, wherein the cutting-off plate is made of a metal.
 - 4. (Canceled)
- 5. (Previously Presented) The fabrication method of the thin film transistor panel according to claim [[4]] 1, wherein the step of exposing the gate pad of the gate pad part comprises the step of removing the insulation film and the gate insulation part formed in the gate pad part by use of dry etching process.
- 6. (Previously Presented) The fabrication method of the thin film transistor panel according to claim [[4]] 1, wherein the step of exposing the data pad protection electrode of the data pad part comprises the step of removing the insulation film formed on the data pad part and the gate insulation film not overlapped with the data pad protection electrode by dry etching process.